

General Description

CMF80R450P is power MOSFET using CMOS's advanced super junction technology that can realize very low on-resistance and gate charge. It will provide much high efficiency by using optimized charge coupling technology.

Features

- $R_{DS(ON)} < 0.4\Omega$ @ $V_{GS} = 11V$
- 100% avalanche tested
- RoHS Compliant
- Low Power Loss by High Speed Switching and Low On-Resistance

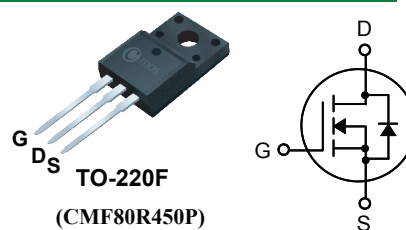
Product Summary

BVDSS	RDSON	ID
800V	0.4 Ω	11A

Applications

- Adaptor
- Motor Control
- DC – DC Converters
- PFC Power Supply Stages
- Switching Applications

TO-220F Pin Configuration



Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DSS}	Drain-Source Voltage	800	V
I _D	Drain Current - Continuous (T _C = 25°C)	11	A
	- Continuous (T _C = 100°C)	7	A
I _{DM}	Drain Current - Pulsed	33	A
V _{GSS}	Gate-Source Voltage	±30	V
E _{AS}	Single Pulsed Avalanche Energy	260	mJ
P _D	Power Dissipation (T _C = 25°C)	35	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Rating	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	3.72	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

Electrical Characteristic (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	800	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 800\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	--	4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance	$V_{GS} = 10\text{ V}, I_D = 7\text{ A}$	--	0.3	0.4	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 15\text{ V}, I_D = 4\text{ A}$	--	9	--	S
R_g	Gate Resistance	$V_{DS}=0\text{ V}, V_{GS}=0\text{ V}, f=1\text{ MHz}$	--	2.1	--	Ω

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}$ $f = 1.0\text{ MHz}$	--	2300	--	pF
C_{oss}	Output Capacitance		--	990	--	pF
C_{rss}	Reverse Transfer Capacitance		--	40	--	pF

Switching Characteristics

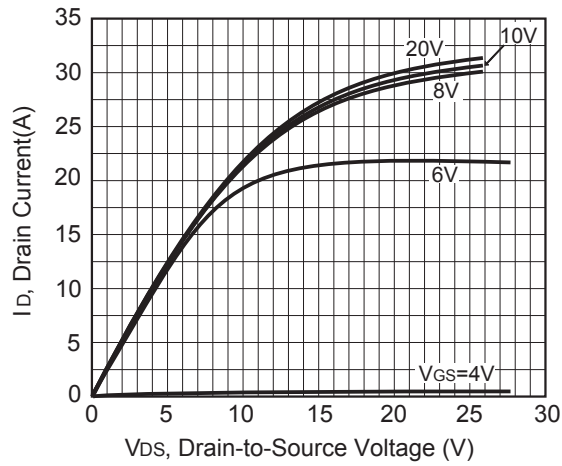
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 400\text{ V}, I_D = 11\text{ A}$ $R_G = 25\text{ }\Omega, V_{GS} = 10\text{ V}$	--	25	--	ns
t_r	Turn-On Rise Time		--	45	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	120	--	ns
t_f	Turn-Off Fall Time		--	45	--	ns
Q_g	Total Gate Charge	$V_{DS} = 640\text{ V}, I_D = 11\text{ A}$ $V_{GS} = 10\text{ V}$	--	38	--	nC
Q_{gs}	Gate-Source Charge		--	7.5	--	nC
Q_{gd}	Gate-Drain Charge		--	16	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

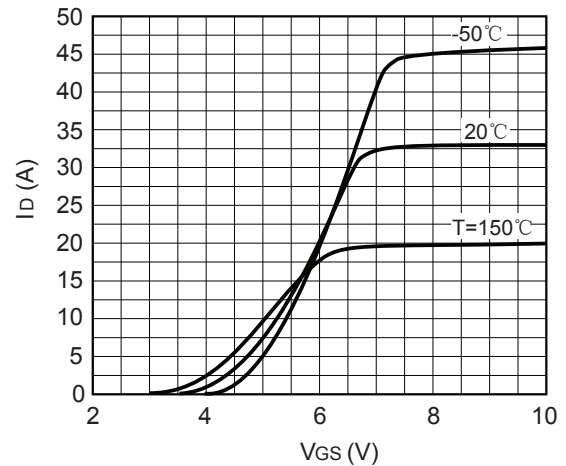
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	11	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	33	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 10A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{DD} = 100V, I _F = 11A	--	356	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	--	4.7	--	μC

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 Cmos assumes no liability for customers' product design or applications.
 Cmos reserves the right to improve product design, functions and reliability without notice.

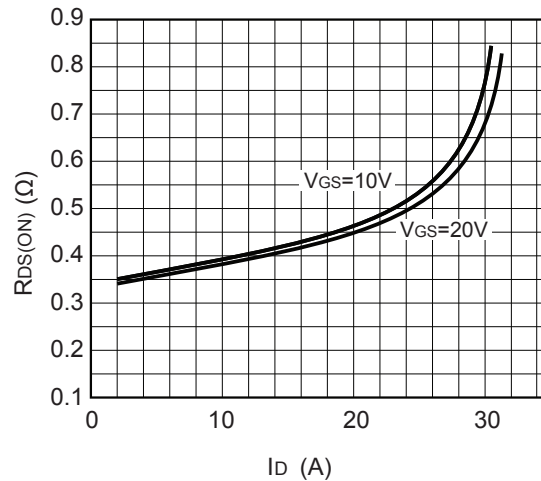
Typical Characteristics



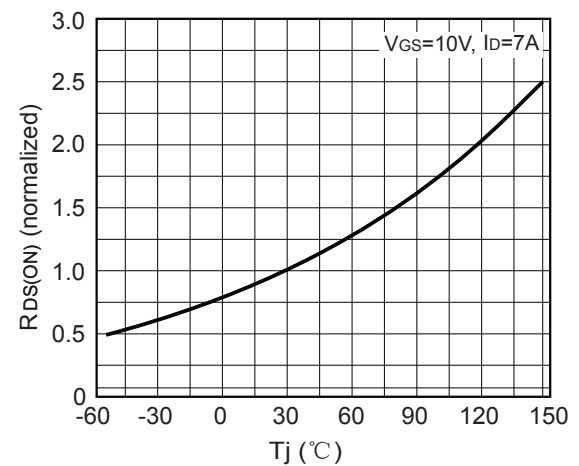
Output Characteristics



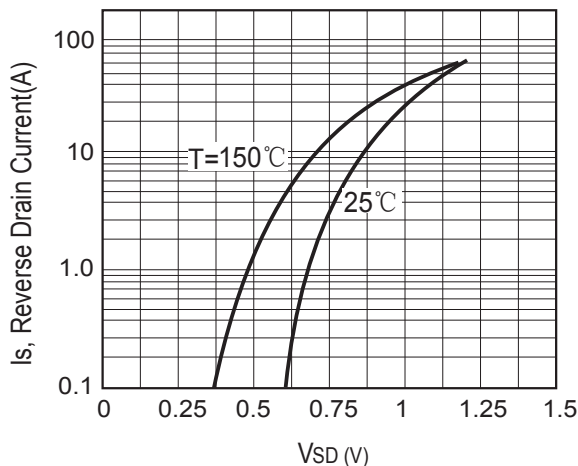
Transfer Characteristics



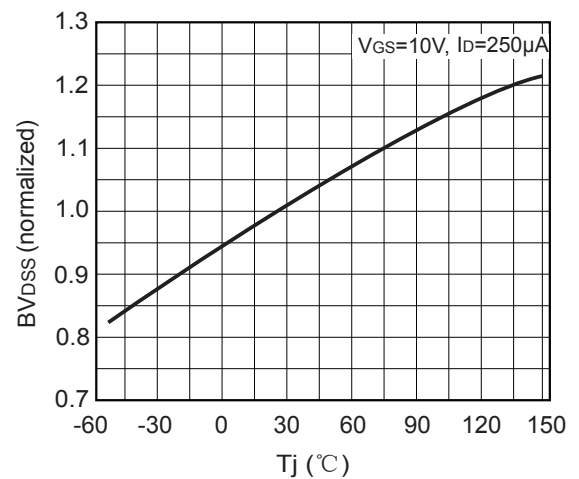
On-Resistance Variation with Drain Current and Gate Voltage



On-Resistance Variation with Temperature

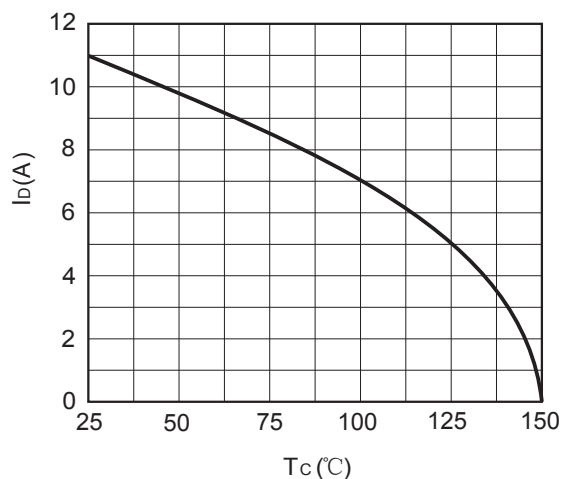


Body Diode Forward Voltage Variation with Source Current and Temperature

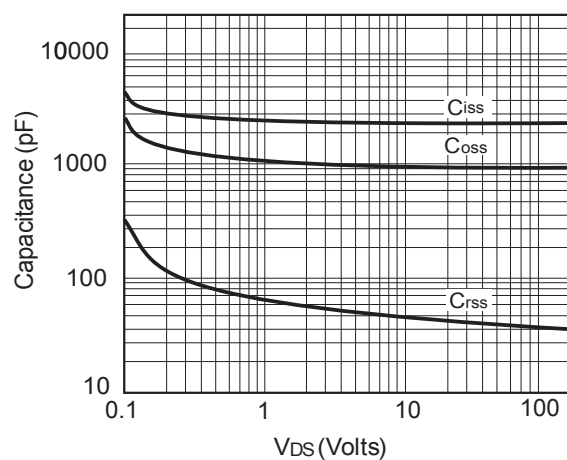


Breakdown Voltage Variation vs Temperature

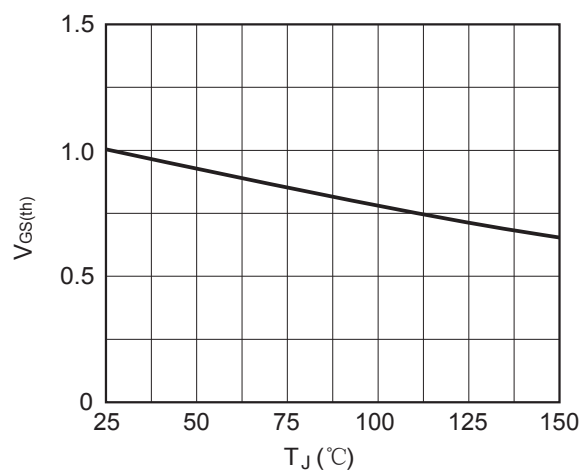
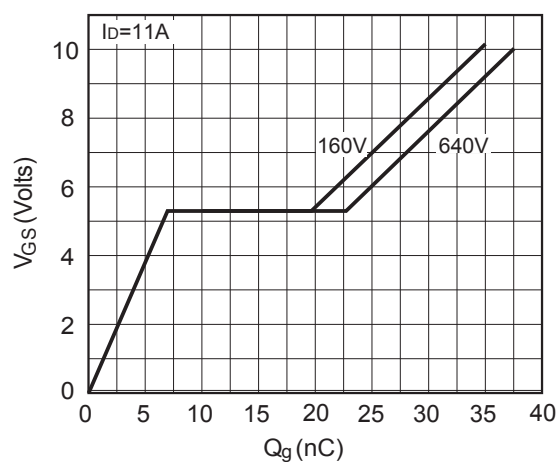
Typical Characteristics



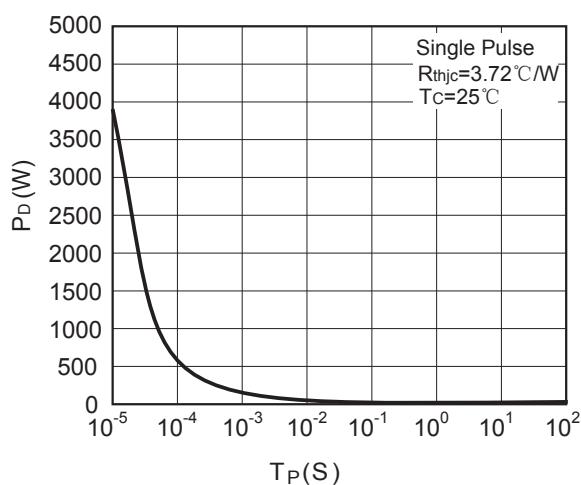
Maximum Drain Current vs. Case Temperature



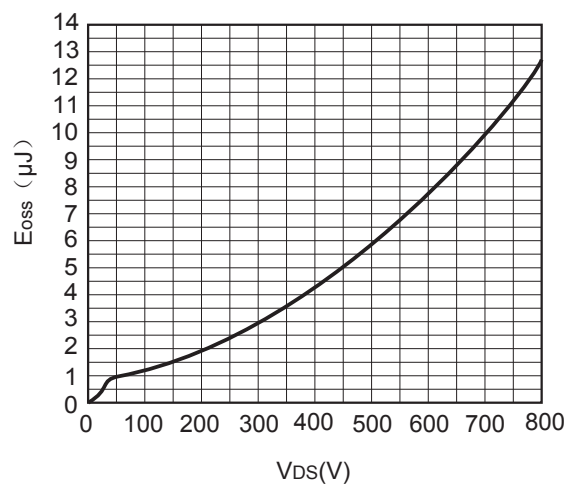
Capacitance Characteristics

 $V_{GS(th)}$ Variation with Temperature

Gate-Charge Characteristics

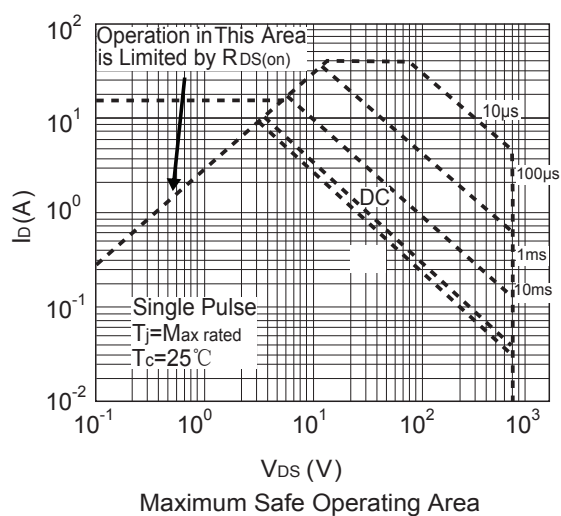
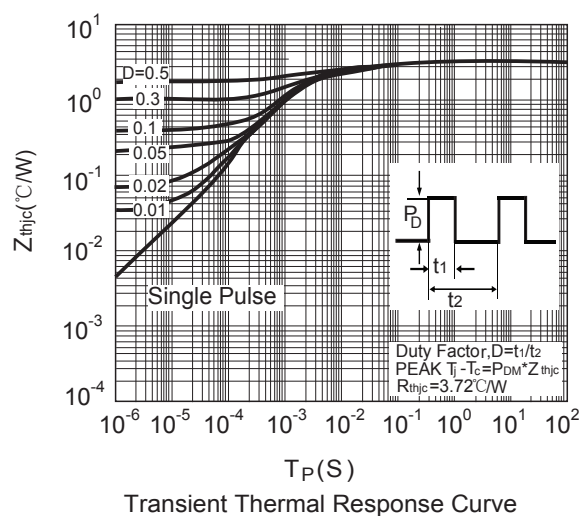


Transient Thermal Response Curve

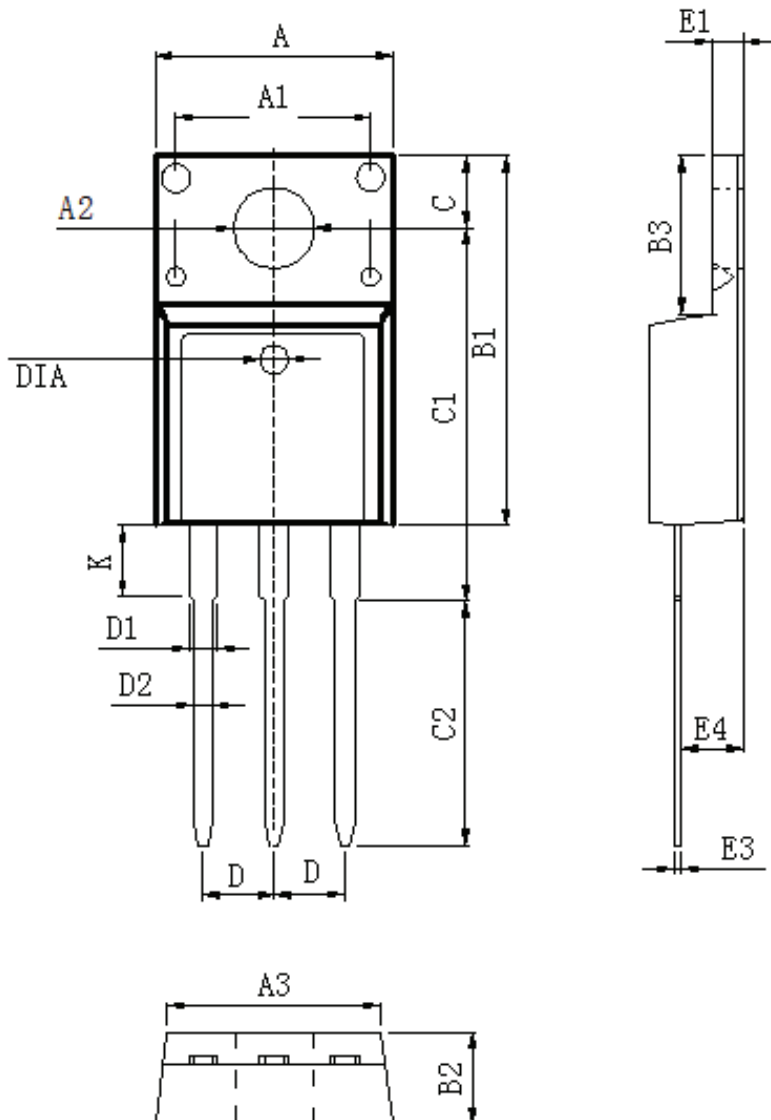


Output Capacitance Stored Energy

Typical Characteristics



Package Dimensions



DIM	MILLIMETERS
A	10.16 ± 0.3
A1	7.00 ± 0.1
A2	3.3 ± 0.2
A3	9.5 ± 0.2
B1	15.87 ± 0.3
B2	4.7 ± 0.2
B3	6.68 ± 0.4
C	3.3 ± 0.2
C1	12.57 ± 0.3
C2	10.02 ± 0.5
D	2.54 ± 0.05
D1	1.28 ± 0.2
D2	0.8 ± 0.1
K	3.1 ± 0.3
E1	2.54 ± 0.1
E3	0.5 ± 0.1
E4	2.76 ± 0.2
DIA	$\odot 1.5$ (deep 0.2)

Unit :mm

Dimensions in Millimeters

